



Material Content Data Sheet



Sales Product Name	TLE4997A8D			Issued	24. January 2018			
MA#	MA001314876							
Package	PG-TDSO-8-2			Weight*	67.77 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.422	3.57	3.57	35739	35739
leadframe	non noble metal	zinc	7440-66-6	0.064	0.10		950	
	non noble metal	tin	7440-31-5	0.080	0.12		1187	
	non noble metal	chromium	7440-47-3	0.097	0.14		1425	
wire	non noble metal	copper	7440-50-8	31.938	47.13	47.49	471289	474851
	noble metal	gold	7440-57-5	0.091	0.13	0.13	1343	1343
encapsulation	organic material	carbon black	1333-86-4	0.061	0.09		906	
	plastics	epoxy resin	-	3.317	4.89		48948	
	inorganic material	silicondioxide	60676-86-0	27.336	40.34	45.32	403369	453223
leadfinish	non noble metal	tin	7440-31-5	0.497	0.73	0.73	7337	7337
plating	noble metal	silver	7440-22-4	0.953	1.41	1.41	14056	14056
glue	plastics	acrylic resin	-	0.228	0.34		3363	
	plastics	epoxy resin	-	0.228	0.34		3363	
	inorganic material	silicondioxide	60676-86-0	0.456	0.67	1.35	6725	13451
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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